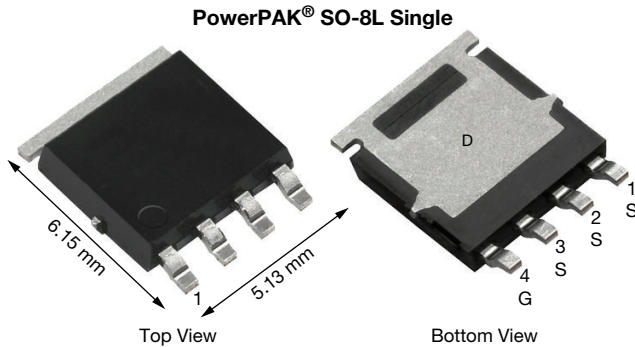


Automotive N-Channel 200 V (D-S) 175 °C MOSFET

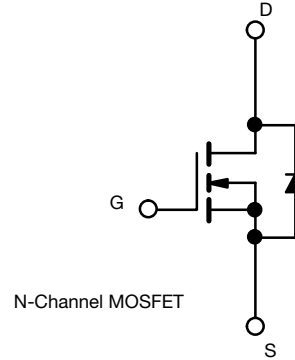


RoHS
COMPLIANT
HALOGEN
FREE



FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



PRODUCT SUMMARY	
V _{DS} (V)	200
R _{DS(on)} (Ω) at V _{GS} = 10 V	0.145
R _{DS(on)} (Ω) at V _{GS} = 4.5 V	0.150
I _D (A)	13
Configuration	Single
Package	PowerPAK SO-8L

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	200	V
Gate-source voltage		V _{GS}	± 20	
Continuous drain current	T _C = 25 °C	I _D	13	A
	T _C = 125 °C		7.5	
Continuous source current (diode conduction) ^a		I _S	60	
Pulsed drain current ^b		I _{DM}	30	
Single pulse avalanche current	L = 0.1 mH	I _{AS}	15	
Single pulse avalanche energy			E _{AS}	
Maximum power dissipation ^b	T _C = 25 °C	P _D	68	W
	T _C = 125 °C		22	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^{d, e}			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount ^c	R _{thJA}	68	°C/W
Junction-to-case (drain)		R _{thJC}	2.2	

Notes

- Package limited.
- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- When mounted on 1" square PCB (FR4 material).
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



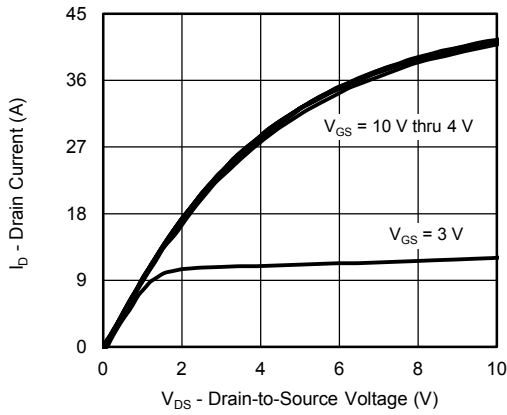
SPECIFICATIONS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0, I_D = 250\text{ }\mu\text{A}$	200	-	-	V	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1.5	2.0	2.5		
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA	
Zero gate voltage drain current	I_{DSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 200\text{ V}$	-	-	1	μA
		$V_{GS} = 0\text{ V}$	$V_{DS} = 200\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$	$V_{DS} = 200\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	250	
On-state drain current ^a	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} \geq 5\text{ V}$	10	-	-	A
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 7.5\text{ A}$	-	0.118	0.145	Ω
		$V_{GS} = 4.5\text{ V}$	$I_D = 5\text{ A}$	-	0.123	0.150	
		$V_{GS} = 10\text{ V}$	$I_D = 7.5\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	-	0.298	
		$V_{GS} = 10\text{ V}$	$I_D = 7.5\text{ A}, T_J = 175\text{ }^\circ\text{C}$	-	-	0.394	
Forward transconductance ^b	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 7.5\text{ A}$		-	33	-	S
Dynamic ^b							
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	-	1990	2600	μF
Output capacitance	C_{oss}			-	133	180	
Reverse transfer capacitance	C_{rss}			-	62	85	
Total gate charge ^c	Q_g	$V_{GS} = 10\text{ V}$	$V_{DS} = 100\text{ V}, I_D = 2\text{ A}$	-	56	85	nC
Gate-source charge ^c	Q_{gs}			-	7	-	
Gate-drain charge ^c	Q_{gd}			-	15	-	
Gate resistance	R_g	$f = 1\text{ MHz}$		0.20	0.45	0.80	Ω
Turn-on delay time ^c	$t_{d(on)}$	$V_{DD} = 100\text{ V}, R_L = 50\text{ }\Omega$ $I_D \cong 2\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		-	14	25	ns
Rise time ^c	t_r			-	5	10	
Turn-off delay time ^c	$t_{d(off)}$			-	33	55	
Fall time ^c	t_f			-	8	15	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed current ^a	I_{SM}			-	-	30	A
Forward voltage	V_{SD}	$I_F = 7.5\text{ A}, V_{GS} = 0$		-	0.83	1.2	V
Body diode reverse recovery time	t_{rr}	$I_F = 5\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		-	86	175	ns
Body diode reverse recovery charge	Q_{rr}			-	335	700	nC
Reverse recovery fall time	t_a			-	64	-	ns
Reverse recovery rise time	t_b			-	22	-	
Body diode peak reverse recovery current	$I_{RM(REC)}$					-	-7.6

Notes

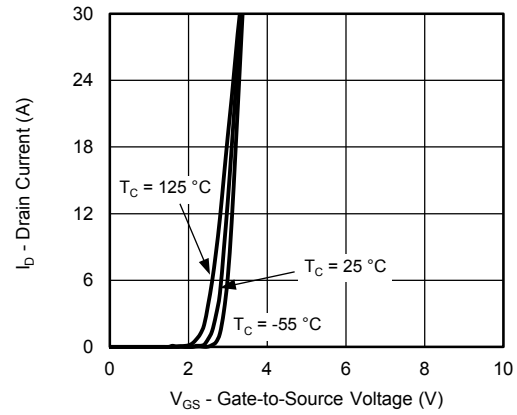
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

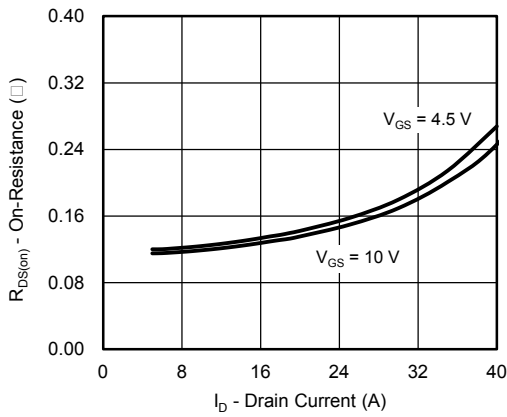
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



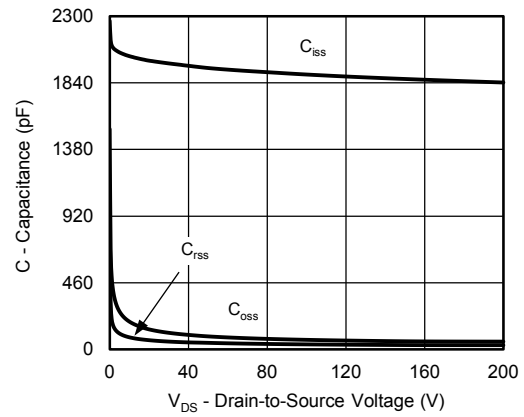
Output Characteristics



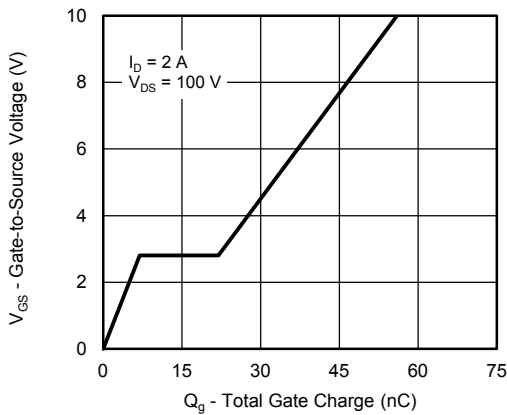
Transfer Characteristics



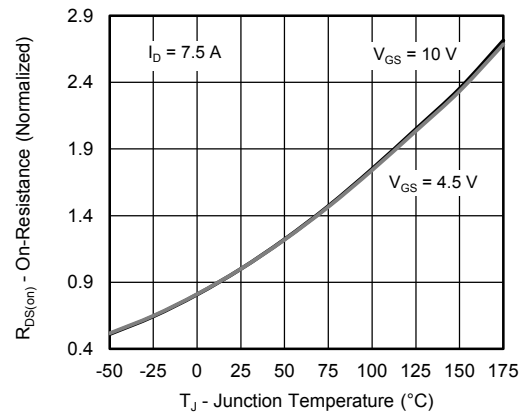
On-Resistance vs. Drain Current



Capacitance

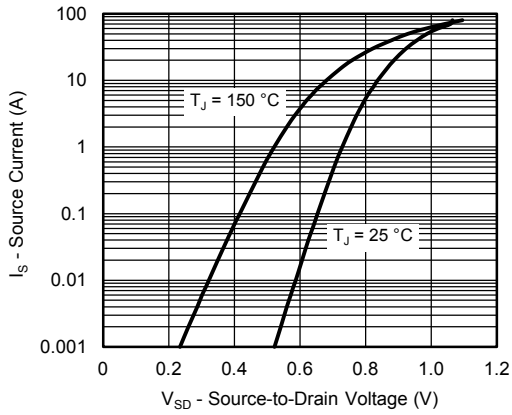


Gate Charge

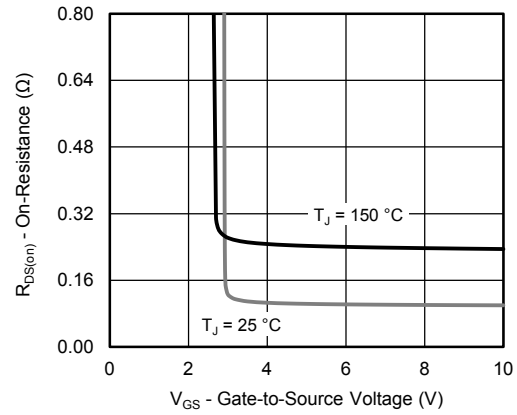


On-Resistance vs. Junction Temperature

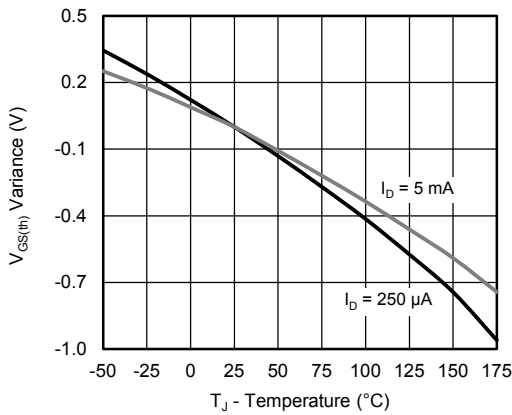
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



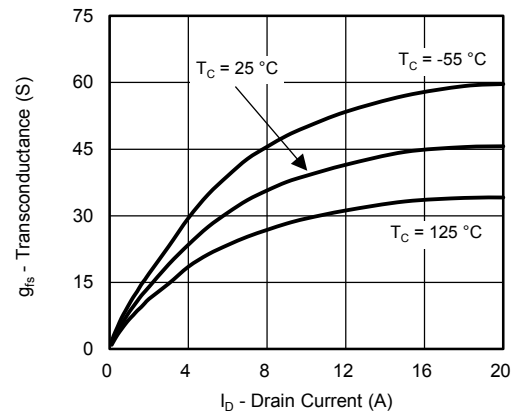
Source Drain Diode Forward Voltage



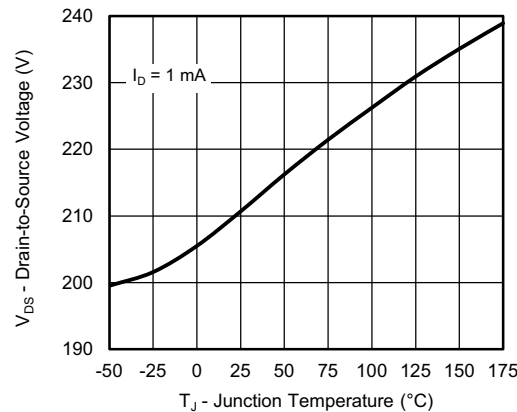
On-Resistance vs. Gate-to Source Voltage



Threshold Voltage



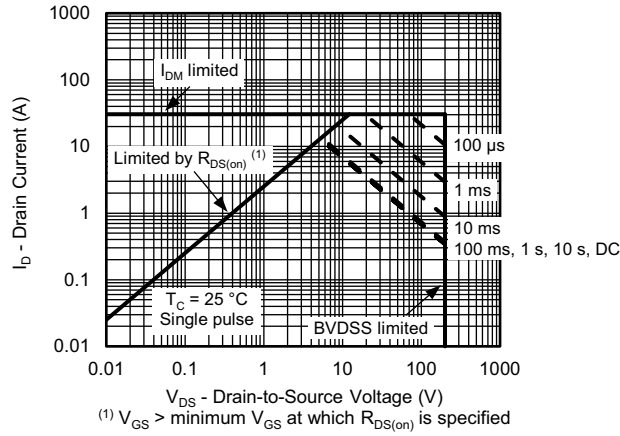
Transconductance



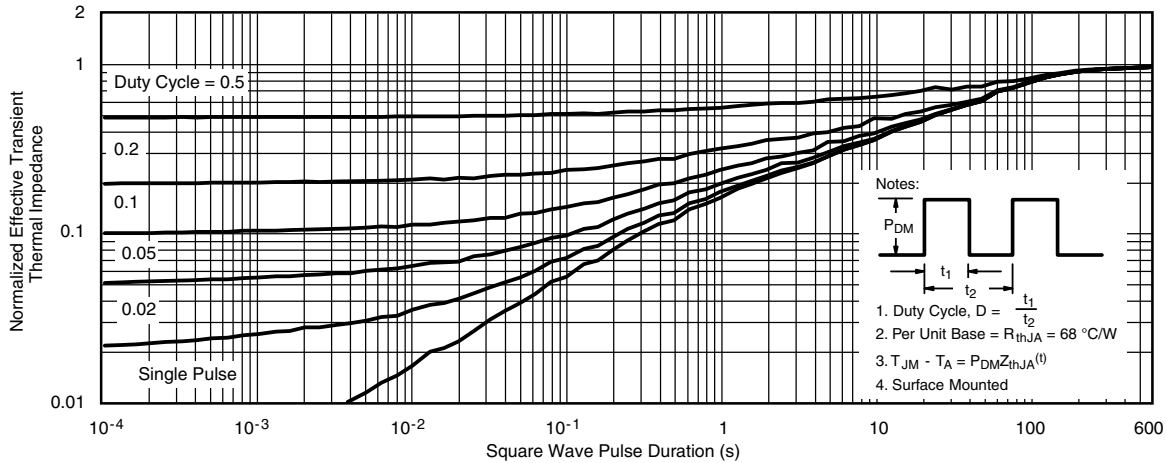
Drain Source Breakdown vs. Junction Temperature



TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



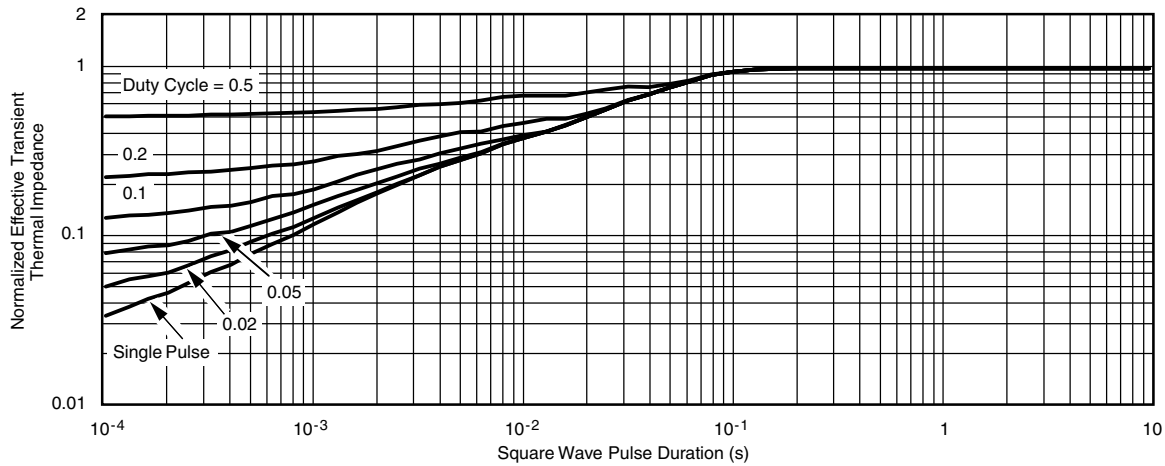
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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